

JC474 U.S. PTO
10/065568



BEST AVAILABLE COPY

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

| | | | | | | |
|---|---------------------------|---|-----------------|-----------------------------------|------|-------------------|
| APPL NUM 10065568 | FILING DATE 10/31/2002 | CLASS 438 | SUBCLASS 684 | GAU 2842 | 282A | EXAMINER LUHRS |
| **APPLICANTS: Chen Kuo-Ming; Liu Hung-Min; | | | | | | |
| **CONTINUING DATA VERIFIED: | | | | | | |
| ** FOREIGN APPLICATIONS VERIFIED: | | | | | | |
| PG-PUB <input type="checkbox"/> | | DO NOT PUBLISH <input type="checkbox"/> | | RESCIND <input type="checkbox"/> | | |
| Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials | | | | ATTORNEY DOCKET NO NAUP0482USA | | |
| TITLE : Solder bump structure and laser repair process for memory device <small>U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)</small> | | | | | | |

| | | | | | |
|---|-----------|--------------------|--|----------------------|----------------------|
| NOTICE OF ALLOWANCE MAILED | | Assistant Examiner | | CLAIMS ALLOWED | |
| | | | | Total Claims | Print Claim for O.G. |
| ISSUE FEE | | Primary Examiner | | DRAWING | |
| Amount Due | Date Paid | | | Sheets Drwg. | Figs. Drwg. |
| <input type="checkbox"/> TERMINAL DISCLAIMER | | PREPARED FOR ISSUE | | Application Examiner | |
| WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only. | | | | | |

FILED WITH: ☐ DISK (CRF) ☐ CD-ROM
(Attached in pocket on right inside flap)